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SUBSTRATES ASSEMBLY APPARATUS



ABSTRACT OF THE DISCLOSURE

A problem occurs that when transferring a large substrate into substrates bonding equipment, and particularly when holding the upper substrate on the pressurizing plate (top table), the top table cannot
5 securely hold the substrate if the substrate bends. In the present invention, the pressurizing plate can securely hold the substrate by providing near the middle of the pressurizing plate (top table) 2 a suction pad
10 which can extend and contract vertically, by extending the suction pad depending on the bending amount of the transferred upper substrate, by supplying negative pressure to the suction holes on the pressurizing plate
and the suction pad to suck the substrate, and then by
15 contracting the suction pad such that the end of the suction pad is positioned at the suction surface of the pressurizing plate.

Figure 3